



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: 40296-0029

Applicant(s): Jung Taik Cheong et al

Confirmation No.: 8083

Appl. No.: 10/608,426

Examiner: Stephen W. Smoot

Filing Date: June 30, 2003

Art Unit: 2813

Title: METHOD FOR FORMING A SEMICONDUCTOR DEVICE WITH A
HARD MASK LAYER FORMED OVER A BIT LINE TO PROTECT
THE BIT LINE DURING SUBSEQUENT ETCHING STEPS

REQUEST FOR CORRECTED FILING RECEIPT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

It is respectfully requested that a corrected Filing Receipt be issued in connection with the captioned application in order to correct the Applicants' name and address:

Please change "Sang Do Lee, Yongin-si, KOREA, REPUBLIC OF" to --Sang Do Lee, Gyeonggi-do, KOREA, REPUBLIC OF--; and

replace "Choi, Seoul, KOREA, REPUBLIC OF" with --Bong Ho Choi, Seoul, KOREA, REPUBLIC OF--.

A copy of the official Filing Receipt is returned herewith together with a copy of the executed Declaration and Power of Attorney. There are no fees believed due in connection with this filing, however, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 08-1641.

U.S. Serial No: 10/608,426
Inventor: Cheong et al.

Attorney Docket No: 40296-0029

Kindly forward the corrected Filing Receipt to the undersigned attorney of record.

Respectfully submitted,

Date: 5/9/05

Heller Ehrman LLP
1717 Rhode Island Avenue, NW
Washington, D.C. 20036
Telephone: (202) 912-2000
Facsimile: (202) 912-2020

Johnny A. Kumar

Johnny A. Kumar
Reg. No. 34,649
Attorney for Applicants

Customer No. 26633



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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/608,426	06/30/2003	2812	900	40296-0029	10	6	1

CONFIRMATION NO. 8083

26633
HELLER EHRMAN WHITE & MCAULIFFE LLP
1666 K STREET, NW
SUITE 300
WASHINGTON, DC 20006

UPDATED FILING RECEIPT



OC000000011564769

Date Mailed: 12/24/2003

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Baig Ho

Gyeonggi-do
Jung Taik Cheong, Seoul, KOREA, REPUBLIC OF;
Sang Do Lee, Yongin-si, KOREA, REPUBLIC OF;
Choi, Seoul, KOREA, REPUBLIC OF;

Domestic Priority data as claimed by applicant

Foreign Applications

REPUBLIC OF KOREA 2002-87094 12/30/2002

If Required, Foreign Filing License Granted: 09/17/2003

Projected Publication Date: 07/01/2004

Non-Publication Request: No

Early Publication Request: No

Title

Method for forming semiconductor device

**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

This license is to be retained by the licensee and may be used at any time on or after the effective date thereof unless it is revoked. This license is automatically transferred to any related applications(s) filed under 37 CFR 1.53(d). This license is not retroactive.

The grant of a license does not in any way lessen the responsibility of a licensee for the security of the subject matter as imposed by any Government contract or the provisions of existing laws relating to espionage and the national security or the export of technical data. Licensees should apprise themselves of current regulations especially with respect to certain countries, of other agencies, particularly the Office of Defense Trade Controls, Department of State (with respect to Arms, Munitions and Implements of War (22 CFR 121-128)); the Office of Export Administration, Department of Commerce (15 CFR 370.10 (j)); the Office of Foreign Assets Control, Department of Treasury (31 CFR Parts 500+) and the Department of Energy.

NOT GRANTED

No license under 35 U.S.C. 184 has been granted at this time, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" DOES NOT appear on this form. Applicant may still petition for a license under 37 CFR 5.12, if a license is desired before the expiration of 6 months from the filing date of the application. If 6 months has lapsed from the filing date of this application and the licensee has not received any indication of a secrecy order under 35 U.S.C. 181, the licensee may foreign file the application pursuant to 37 CFR 5.15(b).



Attorney Docket No.:

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I HEREBY DECLARE:

THAT my residence, post office address, and citizenship are as stated below next to my name;

THAT I believe I am the original, first, and sole inventor (if only one inventor is named below) or an original, first, and joint inventor (if plural inventors are named below or in an attached Declaration) of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD FOR FORMING SEMICONDUCTOR DEVICE

the specification of which (check one)

_____ is attached hereto.

 X was filed on June 30, 2003 as U.S. Serial No. or PCT International Application Number 10/608,426 and was amended on

THAT I do not know and do not believe that the same invention was ever known or used by others in the United States of America, or was patented or described in any printed publication in any country, before I (we) invented it;

THAT I do not know and do not believe that the same invention was patented or described in any printed publication in any country, or in public use or on sale in the United States of America, for more than one year prior to the filing date of this United States application;

THAT I do not know and do not believe that the same invention was first patented or made the subject of an inventor's certificate that issued in any country foreign to the United States of America before the filing date of this United States application if the foreign application was filed by me (us), or by my (our) legal representatives or assigns, more than twelve months (six months for design patents) prior to the filing date of this United States application;

THAT I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment specifically referred to above;

THAT I believe that the above-identified specification contains a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the invention, and sets forth the best mode contemplated by me of carrying out the invention; and

THAT I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I HEREBY CLAIM foreign priority benefits under Title 35, United States Code §119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor's certificate or of

any PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application Number	Country	Foreign Filing Date	Priority Claimed?	Certified Copy Attached?
2002-87094	KR	December 30, 2002	Yes	Yes

I HEREBY CLAIM the benefit under Title 35, United States Code § 119(e) of any United States provisional application(s) listed below.

U.S. Provisional Application Number	Filing Date

I HEREBY CLAIM the benefit under Title 35, United States Code, §120 of any United States application(s), or § 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

U.S. Parent Application Number	PCT Parent Application Number	Parent Filing Date	Parent Patent Number

I HEREBY APPOINT the following registered attorneys and agents of the law firm of **Heller Ehrman White & McAuliffe** to have full power to prosecute this application and any continuations, divisions, reissues, and reexaminations thereof, to receive the patent, and to transact all business in the United States Patent and Trademark Office connected therewith:

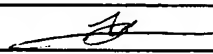
PAUL BOOTH	Reg. No. 40,244
PATRICIA D. GRANADOS	Reg. No. 33,683
JOHN P. ISACSON	Reg. No. 33,715
RONALD J. KAMIS	Reg. No. 41,104
JOHNNY A. KUMAR	Reg. No. 34,649
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COLIN G. SANDERCOCK	Reg. No. 31,298
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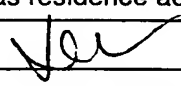
and I request that all correspondence be directed to:

HELLER EHRMAN WHITE & MCAULIFFE
1666 K Street, NW, Suite 300
Washington, DC 20006
Telephone: (202) 912-2000
Facsimile: (202) 912-2020

I UNDERSTAND AND AGREE THAT the foregoing attorneys and agents appointed by me to prosecute this application do not personally represent me or my legal interests, but instead represent the interests of the legal owner(s) of the invention described in this application.

I FURTHER DECLARE THAT all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name of first inventor	Jung Taik CHEONG
Residence	#105-303 Pungrim Apt., Donam-dong, Seongbuk-gu, Seoul 136-061, Korea
Citizenship	Republic of Korea
Post Office Address	Same as residence address
Inventor's signature	
Date	Oct. 24, 2003

Name of second inventor	Sang Do LEE
Residence	#106-604 Daejin 1-cha Apt., Jukjeon-ri, Suji-eup, Yongin-si, Gyeonggi-do 449-845, Korea
Citizenship	Republic of Korea
Post Office Address	Same as residence address
Inventor's signature	
Date	Oct. 24, 2003

Attorney Docket No.:

Name of third inventor

Bong Ho CHOI

Residence

#16-305 Banpo Apt., Banpobon-dong, Seocho-gu, Seoul
137-770, Korea

Citizenship

Republic of Korea

Post Office Address

Same as residence address

Inventor's signature

Date

Oct. 29, 2003